

Refine Search

Search Results -

Terms	Documents
L7	0

Database:

US Pre-Grant Publication Full-Text Database
 US Patents Full-Text Database
 US OCR Full-Text Database
 EPO Abstracts Database
 JPO Abstracts Database
 Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search:

L8

Refine Search

Recall Text

Clear

Interrupt

Search History

 DATE: Monday, June 06, 2005 [Printable Copy](#) [Create Case](#)

<u>Set</u> <u>Name</u>	<u>Query</u>	<u>Hit</u> <u>Count</u>	<u>Set</u> <u>Name</u> result set
side by side			
	DB=TDBD; PLUR=YES; OP=OR		
<u>L8</u>	<u>L7</u>	0	<u>L8</u>
	DB=DWPI; PLUR=YES; OP=OR		
<u>L7</u>	<u>L6</u>	0	<u>L7</u>
	DB=JPAB; PLUR=YES; OP=OR		
<u>L6</u>	<u>L5</u>	0	<u>L6</u>
	DB=EPAB; PLUR=YES; OP=OR		
<u>L5</u>	<u>L4</u>	0	<u>L5</u>
	DB=USOC; PLUR=YES; OP=OR		
<u>L4</u>	<u>L3</u>	0	<u>L4</u>
	DB=PGPB; PLUR=YES; OP=OR		
<u>L3</u>	<u>L2</u>	0	<u>L3</u>
	DB=USPT; PLUR=YES; OP=OR		
<u>L2</u>	L1 and (wafer same via same ("bonding pad" or "bonding pads"))	12	<u>L2</u>

L1 ("microchip" or "microdie" or "micro device" or "micro chip" or " micro
die") same wafer

820 L1

END OF SEARCH HISTORY

Refine Search

Search Results -

Terms	Documents
passivation and 6777263	0

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 IBM Technical Disclosure Bulletins

Search:

L13

Search History

DATE: Monday, June 06, 2005 [Printable Copy](#) [Create Case](#)

Set Name Query

side by side

Hit Count Set Name

result set

DB=USPT; PLUR=YES; OP=OR

<u>L13</u>	passivation and 6777263	0	<u>L13</u>
<u>L12</u>	5801068 and passivation	0	<u>L12</u>
<u>L11</u>	L6 and passivation	0	<u>L11</u>
<u>L10</u>	("anodic bonding" near10 seal\$5) same packag\$5	11	<u>L10</u>
<u>L9</u>	"anoding bonding" near10 sealant	0	<u>L9</u>
<u>L8</u>	("glas frit" near10 seal\$5) same packag\$5	0	<u>L8</u>
<u>L7</u>	"glas frit" near10 sealant	0	<u>L7</u>
<u>L6</u>	5144412 and seal\$6	5	<u>L6</u>
<u>L5</u>	L4 and "bonding pad"	12	<u>L5</u>
<u>L4</u>	L3 and via	116	<u>L4</u>
<u>L3</u>	L1 same packag\$5 same "cup"	286	<u>L3</u>
<u>L2</u>	L1 packag\$5 same "cup"	448194	<u>L2</u>
<u>L1</u>	chip or die	444766	<u>L1</u>

END OF SEARCH HISTORY

Refine Search

Search Results -

Terms	Documents
L4 and "bonding pad"	12

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Search:

L5

Refine Search

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DATE: Monday, June 06, 2005 [Printable Copy](#) [Create Case](#)

Set Name Query
side by side

Hit Count Set Name
result set

DB=USPT; PLUR=YES; OP=OR

<u>L5</u>	L4 and "bonding pad"	12	<u>L5</u>
<u>L4</u>	L3 and via	116	<u>L4</u>
<u>L3</u>	L1 same packag\$5 same "cup"	286	<u>L3</u>
<u>L2</u>	L1 packag\$5 same "cup"	448194	<u>L2</u>
<u>L1</u>	chip or die	444766	<u>L1</u>

END OF SEARCH HISTORY